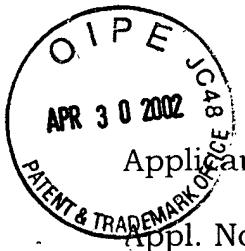


#7/A  
5-19-02  
R. Geller  
PATENT  
0033-0694P



IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant:

SUMIKAWA, et al.

Conf.: 2465

Appl. No.:

09/782,180

Group: 2814

Filed:

February 14, 2001

Examiner: D. NGUYEN

For:

SEMICONDUCTOR DEVICE AND METHOD OF  
MANUFACTURING THE SAME

REPLY UNDER 37 C.F.R. § 1.111

Assistant Commissioner for Patents  
Washington, DC 20231

April 30, 2002

Sir:

In reply to the Office Action mailed January 30, 2002, the following amendments and remarks are submitted.

IN THE CLAIMS:

Please amend the claims as follows:

1. (Amended) A semiconductor device comprising:  
a semiconductor substrate having a surface provided with an external connection electrode and;  
a surface opposite that with said external connection electrode, abrased with a mirror finish and reinforced with a back-surface reinforcement member.

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